



Docket No.: M4065.0248/P248-C  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Patent Application of:  
Allen McTeer

Application No.: 10/656,182

Confirmation No.: 8422

Filed: September 8, 2003

Art Unit: 2815

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For: A MULTI-LAYERED COPPER BOND PAD  
FOR AN INTEGRATED CIRCUIT

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Examiner: E. Lee

**AMENDMENT AFTER FINAL ACTION (37 C.F.R. § 1.116)**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated November 29, 2005, finally rejecting claims 74-80, 82 and 83, please amend the above-identified U.S. patent application as follows:

**Amendments to the Drawings** begin on page 2 of this paper and included an attached replacement sheet.

**Amendments to the Specification** begin on page 3 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.